ES 2017 The 5th International Conference on Enterprise Systems
Sep 22-24, 2017 | Beijing, China
www.ie.tsinghua.edu.cn/es2017

Call for Papers

Welcome to ES2017

ES2017 will be held in Beijing, China Sep 22-24, 2017. The ES2017 is co-organized by ABB and Tsinghua University, China, and hosted by Tsinghua University. The theme of ES 2017 is "Made in China 2025 and Industry 4.0". The world’s public authorities, industries, researchers and academia are cordially invited to participate in a wealth of presentations, tutorials, special sessions, social activities and to enjoy the unique cultural experiences in Beijing. It has been highlighted by the IEEE Systems, Man, and Cybernetics Society: http://ieeesmc.org/

Who and why should attend

The ES2017 is unique compared with conventional academic conferences and industrial fairs, featured by three units: Academic Forum, Industry Forum, and Innovation & Entrepreneurship Forum. It will be a great venue for:

Professors, researchers, and students

- To meet Fellows of national academies, Editor-in-Chief(s) of IEEE Transactions, and Fellows of IEEE
- To learn how to turn your research results into publications in top journals.

Developers, engineers and practitioners

- To meet global industrial giants in a compete value chain like ABB, AVIC, CASIC, CRRC, Google, Huawei, Microsoft, SAP, etc.
- To find opportunities of partnership e.g. join their eco-systems and providing complementary products, services, distribution channels, and system integration.

Investors and incubators

- To meet high level officials for updated public policies about Industry4.0 and Made-in-China2025
- To meet many ambitious and innovative researchers and potential entrepreneurs who could become the next unicorn.

Entrepreneurs

- To meet the active investors from China and the world in the areas of TMT, smart manufacturing, intelligent devices, etc.

Important Dates

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<th>Event</th>
<th>Date</th>
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<tr>
<td>Paper submission due</td>
<td>May 31, 2017(pased)</td>
</tr>
<tr>
<td>Notification of acceptance</td>
<td>July 7, 2017</td>
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<td>Final manuscript due</td>
<td>July 31, 2017</td>
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<tr>
<td>Registration due</td>
<td>Aug 22, 2017</td>
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<td>Conference date</td>
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Committees

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Publications

We welcome both survey and original articles. Accepted papers will be submitted for inclusion into the IEEE Xplore Database which is indexed by EI. Authors of selected papers will be invited to submit an extended version to top international journals in these areas. All manuscripts shall be written in English, using the IEEE conference template (double column, size 10). The limits of length are: 8 pages long paper aiming for journal publication, 6 pages full paper, and 4 pages work-in-progress papers.

Scope

The theme of ES2017 is Made in China 2025 and Industry 4.0. We welcome original and survey articles about the latest advances of technology. The results can be state-of-the-art, requirements, fundamental theories, models, frameworks, algorithms, methodologies, platforms, protocols, prototypes, testbeds, field trials, case studies/stories, field experiences, standardization efforts, regulatory activities, education and training innovations, etc. The application areas include aeronautics and astronautics, agriculture, automotive, building, construction, energy, finance, healthcare, logistics, manufacturing, process industry, power, transportation, etc.

The topics of interest include but are not limited to:
1. Enterprise Systems for Industry 4.0
2. Cyber Physical Systems for Industry 4.0
3. Internet of Things for Industry 4.0
4. Big Data for Industry 4.0
5. Security and Privacy Protection for Industry 4.0
6. System Engineering, Human Factors for Industry 4.0
7. IoT-enabled Smart Manufacturing
8. Made in China 2025 and Heathy China 2030

Special Sessions

Approved special sessions:
1. SS on Big Data in Smart Grid
2. SS on Industry4.0 for healthcare and aging population
3. SS on The Advanced Informatization of Railway Industry
4. SS on Big Data and IIoT for the Ocean
5. SS on Cloud Manufacturing and Industrial 4.0
6. SS on Sensing and Data Analytics for Precision Medicine
7. SS on IT Operations Management(ITOM)
8. SS on Industrial IoT and Smart City
9. SS on Intelligent Equipment Modeling, Informatics and Control
10. SS on Human Factors and Ergonomics in Systems
11. SS on Indoor Localization and Navigation
12. SS on IIoT for Smart Manufacturing

We are calling for more special sessions to provide a focused discussion of new or innovative topics. Special Session organizers consist of at least five papers. All Special Session papers will be reviewed with the same criteria as Regular Session papers. Please submit your proposal by Mar 31, 2017 to Special Session Chair, Prof. Jiafu Wan, South China University of Technology, mejwan@scut.edu.cn

Invited Speakers

Prof. M. Jamal Deen, Ph.D.
President – Academy of Science, Royal Society of Canada
Title: Mega trends, challenges, and strategies for research and innovation in the era of Industry 4.0

Dr. Chunyuan Gu, Ph.D.
Member of the Royal Swedish Academy of Engineering Sciences (IVA) | Senior VP of ABB Group | President of ABB China
Title: Digitalization and re-industrialization

Prof. Victor C. M. Leung, Ph.D.
Fellow of the Royal Society of Canada
Title: Cloud Enabled Smart Transportation for Industry 4.0

Prof. Bohu Li, Ph.D.
Academician of Chinese Academy of Engineering China Aerospace Science & Industry Corp. (CASIC)
Title: Smart Cloud Manufacturing — A kind of Industrial Internet with Chinese characteristics

Prof. Branka Vucetic, Ph.D.
Fellow of Australian Academy of Technological Sciences and Engineering
Title: Communications for Industrial Internet of Things and Industry 4.0: the 5G and beyond

Dr. Xinguo Zhang
Senior Executive Vice President R&D and CIO of Aviation Industry Corporation of China(AVIC)
Title: Enterprise System Analysis, Modeling and Simulation

Prof. Yuan-Ting Zhang, Ph.D.
Editor-in-Chief, IEEE Reviews in Biomedical Engineering
Past EIC of IEEE TITB, Past EIC of IEEE JBHI
Title: Health Convergence in the Era of Industry 4.0: Challenges and Opportunities

More speakers to be confirmed, find the updated list on the website...

For more information, please visit www.ie.tsinghua.edu.cn/es2017